

ABSTRACT

A semiconductor chip having a planar active surface including an integrated circuit; the circuit has
5 metallization patterns including a plurality of contact pads. Each of these contact pads has an added conductive layer on the circuit metallization. This added layer has a conformal surface adjacent the chip and a planar outer surface, and this outer surface is suitable to form
10 metallurgical bonds without melting. The chip contact pads may have a distribution such that an area portion of the active chip surface is available for attaching a thermally conductive plate; this plate has a thickness compatible with the thickness of the conductive pad layer.

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